Atmel			™ MICROC	HIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	PDIP 300 MIL	XXXXXXXXX XXXXXXXXX AA AA AA AA	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Class Code, Date Code ● = Pin 1 indicator OR Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information Bottom Mark Lot Number Country of Origin in the injector mold	XXXXXXXXX XXXXXXXXX YYWWNNN	Top Mark Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability
		C C C C C C C C C C C C C C C C C C C	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Device Information Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	XXXXXXXXX XXXXXXXXX YYWWNNN F-G-G-G-G-G-G-G-G-G-G-G-G-G-G-G-G-G-G-G	Top Mark Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information ■ ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	C C C C C C C C C C C C C C C C C C C	Bottom Mark No bottom mark Country of Origin in injector mold Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ■ = Pin 1 location OR Top Mark Line 1= Atmel Logo, Device Information Line 2 = Device Name Line 3 = Lot Traceability
					Bottom Mark No bottom mark Country of Origin in injector mold

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
14	PDIP 300 MIL	AME YYWW# XXXXXXXXXX XXXX AAAAAAA AAAAAAAA	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ■ ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	THE XXXXXX XXX XXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ■ = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold
20	PDIP 300 MIL	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ■ ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	THE XXXXXX XXXXXXX XXX YYWWNNN TO CO	Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ■ = Pin 1 location OR Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability Bottom Mark No bottom mark
24	PDIP300 MIL	XXXXXX O O AAAAAA	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ■ ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	AMEL XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability ■ = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold

Atmel®			MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
28 / 32	PDIP 600 MIL	XXXXXX AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin in injector mold, Lot Traceability	AAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability o = Pin 1 indicator Bottom Mark No bottom mark
40	PDIP 600 MIL	AAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA	Top Mark Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	AAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA	Top Mark Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
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		Atmel	MICRO	HIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXX AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold, Lot Traceability	AAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability o = Pin 1 indicator Bottom Mark No bottom mark
		**** **** **** **** **** **** ****	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold, Lot Traceability	AAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA	Top Mark Line 1 = Atmel Logo Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No Bottom Mark
28	SPDIP	XXXXXX O O AAAAAA	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ■ ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	THE XXXXXX XXX XXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ■ = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold

Atmel			MICROC	HIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	SOIJ	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator Bottom Mark Lot Number Country of Origin in the injector mold		Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Voltage Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
		ATMELYYWW# XXXXXXX XXXXX AAAAAA HHHHHHHHHHHHH	Top Mark Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O ▲ = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	ATMELXXX XXXXXXX YYWWNNN CO	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

	Atmel	MICROCHIP		
Lead/Pin/ Bump Count Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8 SOIC	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Class Code, Date Code or Lot Traceability O = Pin 1 indicator Bottom Mark Lot Number Country of Origin in injector mold	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator OR Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Device Information Line 3 = Lot Traceability OR Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold
		Top Mark Line 1= Subcon Code Line 2 = Date Code O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold		Top Mark Line 1= Country of Origin Line 2 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

	Atmel®			MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		ATMELYYWW# XXXXXXXX XXXXX AAAAAA AAAAAA	Top Mark Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = AAAAAAA = Lot Traceability	ATMELXXX XXXXXXXXX YYWWNNN	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
14	SOIC 150 MIL	ATMELYYWW# XXXXXXXX AXXXXX HHHHHHHH XXXXXX AAAAAA XXXXX AAAAAAA	Top Mark Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O ▲ = Pin 1 indicator Bottom Mark XXXXX = Country of Origin if not in injector mold Country of Origin in injector mold AAAAAAA = Lot Traceability	ATMELXXXXXXX XXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1 = ATMEL, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
16 / 20 / 24 / 28	SOIC 300 MIL	ARRABA XXXXXX YYWW# XXXXXXXX-XXXX AAAAAA HHHHHHHHHHHHHHH	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator Bottom Mark Line 1 = XXXXX Country of Origin in injector mold Line 2 = Lot Traceability	ARRENA XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability O = Pin 1 indicator OR Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold

	Atmel			MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXX XXXXXXXXX XXXXXXXXX	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code ● = Pin 1 indicator	XXXXXXXXX XXXXXXXX XXXXXXXX	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code, Country of Origin ● = Pin 1 indicator
		Atmel XXXXXXXXXXXX XX YYWWX X ⊕ AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator	Atmel XXXXXXXXXXXX XX YYWW X YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator
			Top Mark Line 1= Device Name Line 2 = Date Code, Lot Traceability O = Pin 1 indicator	A A A A A A A A A A A A A A A A A A A	Top Mark Line 1= Device Name Line 2 = Lot Traceability O = Pin 1 indicator
		○ YYWW AAAAAA ■ 日 日 日 日 日 日 日 日 日 日 日 日 日 日 日 日 日 日 日	Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		Bottom Mark No bottom mark Country of Origin in injector mold

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		AMEL XXXXXXXXXXX YYWW AAAAAA HHHHHHHHHHHHHHH AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator	A A A A A A A A A A A A A A A A A A A	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator
			Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		Bottom Mark No bottom mark Country of Origin in injector mold
28	SSOP 208 MIL	ATMEL XXXXXXXXXX YYWWX AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator	ATMEL XXXXXXXXXX YYWW YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code Line 4 = Lot Traceability O = Pin 1 indicator
			Bottom Mark No bottom mark Country of Origin in injector mold		Bottom Mark No bottom mark Country of Origin in injector mold

	Atmel			MICROCH	HP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	TSSOP	OXXXX AA AA AA	Top Mark Line 1= Class Code, Date Code Line 2 = Truncation Code O = Pin 1 indicator OR Line 1= Truncation Code Line 2 = Device Name	XXXXXXXX TO THE TOTAL TO	Top Mark Line 1= AT, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
		AT * Y W W XXXXXXX AAAAAA	Bottom Mark Lot Traceability Country of Origin in injector mold Top Mark Line 1= AT, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	AT * Y W W XXXXXXX Y Y W W N N N	Top Mark Line 1= AT, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
		YMTC	Top Mark Line 1= Subcon Code Line 2 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	YYWWNNN STATE OF THE STATE OF T	Country of Origin in injector mold Top Mark Line 1= Country of Origin Line 2 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold
		XXXXX XXXX XXXX XXXX	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name (shortened) Line 3 = Device Information Bottom Mark No bottom mark Country of Origin in injector mold	XXXX XXXX WNNN	Top Mark Line 1= Device Information Line 2 = Device Name (shortened) Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold
14	TSSOP	AT YYWW# XXXXXXXX XXXX AAAAAA	Top Mark Line 1 = AT, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	ATMELXXX XXXXXXXX YYWWNNN	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

Atmel				MICROC	HIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
16	TSSOP	XXXXXX AAAAAA	Top Mark Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	ATMELXXX XXXXXXXXX Q	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
20	TSSOP	XXXXXXXX YYWW AAAAAAA AAAAAA	Top Mark Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXX YYWW YYWWNNN	Top Mark Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark Country of Origin in injector mold
		XXXXXX XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	ATMELXXX XXXXXXXXX YYWWNNN	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

Atmel				MICROCH	IIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
20 / 24	TSSOP	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1 = Device Name Line 2 = Device Information, Country Code Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
28 / 32	TSOP		Top Mark Line 1 = ATMEL Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) O = Pin 1 indicator ▲ = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1 = ATMEL Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	SOT-23	THE YMTC	Top Mark Line 1= Truncation Code, Class Code • = Pin 1 indicator Bottom Mark Lot Traceability (Year, Month, Trace Code)	A A A XXXXYY WWNNN	Top Mark Line 1= Truncation Code, Subcon Code, Year Line 2 = Lot Traceability
		XYMTC H	Top Mark Line 1= Lot Traceability (Year, Month, Trace Code) Bottom Mark No bottom mark	CC YY WWNNN	Top Mark Line 1= Country Code, Year Line 2 = Lot Traceability Bottom Mark No bottom mark

	Atmel®			MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
5	SOT-23	A A A A A A A A A A A A A A A A A A A	Top Mark Line 1= Truncation Code, Device Information • = Pin 1 indicator Bottom Mark Lot Traceability (Year, Month, Trace Code)	A A A A A A A A A A A A A A A A A A A	Top Mark Line 1= Truncation Code, Device Information, Year Line 2 = Lot Traceability (Workweek, Lot Number)
		A A A A A A A A A A A A A A A A A A A	Top Mark Line 1= Truncation Code, Device Information Line 2 = Lot Traceability (Year, Month, Trace Code) Bottom Mark No bottom mark	H H H H	Top Mark Line 1= Truncation Code, Lot Traceability ■ = Pin 1 indicator Bottom Mark No bottom mark
6	SOT-23	XXXX AAAAA	Top Mark Line 1= Device Name (shortened) o = Pin 1 indicator Bottom Mark Lot Traceability	XXXY WWNNN O	Top Mark Line 1= Device Name (shortened) Lie 2 = Lot Traceability o = Pin 1 indicator Bottom Mark No bottom mark
8	VFBGA	XXXX XYMTC •	Top Mark Line 1= Truncation Code, Device Information Line 2 = Lot Traceability ■ = Pin 1 indicator	XXXX WWNNN	Top Mark Line 1= Truncation Code, Device Information, Year Line 2 = Lot Traceability ■ = Pin 1 indicator
49	VFBGA 5X5 MM	T YYWW## XXXXXXXXX XXXX-X AAAAA	Top Mark Line 1= AT, Date Code, Die Revision, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ■ = Pin 1 indicator	● ATMEL XXXXXX XX-COO XXXXXX YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator

Atmel				MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
96	VFBGA 6X6 MM	LIMES XXXXXXXXXX YYWWX X AAAAAA	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability ■ = Pin 1 indicator	LIMES XXXXXXXXXX YYWW X YYWWNNN	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability ■ = Pin 1 indicator	
100	VFBGA 7X7 MM	Atmel XXXXXXXXXXX XXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXXX XXX YYWW X YYWWNNN ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	
		Atmel XXXXXXXXXXX XXX YYWWX X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXXX XXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	

		Atmel		MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
		•	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 3 = Country of Assembly Line 4 = Lot Traceability Line 5 = Die ID, Revision ● = Pin 1 indicator	AMEL XXXXXXX X-COO XXXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator	
40	TFBGA 4X4 MM	• XXXXXX XXXXXX AAAAA X YYWW	I	XXXXXX XXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code ● = Pin 1 indicator	
256	TFBGA 8X8 MM	Atmel XXXXXXXXXX XX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	
100	TFBGA 9X9 MM	<pre> /tmel xxxxxxxxxxxx xxxxxx yywwx x AAAAAA ARM </pre>	Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXXX XXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	

Atmel®				MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	● XXXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
		**************************************	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 3 = Country of Assembly Line 4 = Lot Traceability Line 5 = Die ID, Revision ● = Pin 1 indicator	• AMEL XXXXXXX XXX-COO XXXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ■ = Pin 1 indicator
144 T	TFBGA 10X10 MM	MICROCHIP XXXXXXXXXX XXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Subcon Code, Design Revision Line 6 = Lot Traceability, ARM ● = Pin 1 indicator	MICROCHIP XXXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Design Revision Line 6 = Lot Traceability, ARM ■ = Pin 1 indicator
		Atmel XXXXXXXXXXXX XXXXXXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	Atmel XXXXXXXXXXXX XXXXXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator

Atmel				MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
176	TFBGA 11X11 MM	MICROCHIP XXXXXXXXXX XXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Subcon Code, Design Revision Line 6 = Lot Traceability, ARM ■ = Pin 1 indicator	MICROCHIP XXXXXXXXXX XXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Design Revision Line 6 = Lot Traceability, ARM ■ = Pin 1 indicator
196	TFBGA 11X11 MM	Atmel XXXXXXXXXX XX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XX YYWW X YYWWNNN ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
		Atmel XXXXXXXXXX XXXXXX YYWWX-X X AAAAAA ARM ■	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XXXXXX YYWW-X YYWWNNN ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator

Atmel®			MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
144	TFBGA 12X12 MM	XXXXXXXX XXXX XXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	XXXXXXXX XXXX XXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
324	TFBGA 12X12 MM		Top Mark		Top Mark
		<pre> Atmel XXXXXXXXXX XXXXXX YYWWX X AAAAAA ARM </pre>	Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM ●	Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
361	TFBGA 16X16 MM	Atmel XXXXXXXXXX XX YYWWX X AAAAAA ARM ■	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
144	LFBGA 10X10 MM	Atmel XXXXXXXXXXXX XXXXXXXXX YYWWX X AAAAAA ARM ■	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXXXX XXXXXXXXXX YYWW X YYWWNNN ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator

Atmel				MICROC	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)		
289	LFBGA 14X14 MM	Atmel XXXXXXXXXX XXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XXXXXX YYWW X YYWWNNN ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator		
		Atmel XXXXXXXXXX XXXXXX YYWWX-X X AAAAAA ARM ■	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XXXXXX YYWW-X X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator		
217	LFBGA 15X15 MM	Atmel XXXXXXXXXXXXX XXX YYWWX AAAAAA ARM OR Atmel XXXXXXXXXXX XX YYWWX AAAAAA ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXXXXX XXX YYWW X YYWWNNN ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		
256	LFBGA 15X15 MM	Atmel XXXXXXXXX XXXXXXX YYWWX-X X AAAAAA ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXX XXXXXXX YYWW-X X YYWW-X X YYWWNNN ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator		

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	Atmel XXXXXXXXX XX YYWW X YYWWNNN ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
		Atmel XXXXXXXX YYWWX X AAAAAA ARM ■	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM ■ = Pin 1 indicator
15	UFBGA 3X3 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device Type Code Line 3 = Lot Traceability ■ = Pin 1 indicator	• XXXX XXXX YWWNNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability ■ = Pin 1 indicator
32	UFBGA 4X4 MM	•XYWW# XXXXX XXXXX AAAAA	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information, Die Revision Line 4 = Lot Traceability ■ = Pin 1 indicator	•ATMEL XXXX XXXX YWWNNN	Top Mark Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability

	Atmel®			MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
49	UFBGA 5X5 MM	• AT YYWW## XXXXXXXXX XXXXX—X AAAAAA	Top Mark Line 1= AT, Date Code, Die Revision, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXX XX-COO XXXXXX YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ■ = Pin 1 indicator
144	UFBGA 6X6 MM	Atmel XXXXXXXXXXX XXX XXX YYWWXX AAAAAA ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	Atmel XXXXXXXXXXX XXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator
36	WLGA 6.5X3.5 MM	•AT XXXXX XXXXYWWX AAAAA	Top Mark Line 1= AT, Device Name (shortened) Line 2 = Device Information, Date Code, Die Revision Line 3 = Lot Traceability ● = Pin 1 indicator	• AT XXXXX XXX-COO YYWWNNN	Top Mark Line 1= AT, Device Name (shortened) Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability ■ = Pin 1 indicator

		Atmel	MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
4	WLCSP	● C YTC	Top Mark Line 1= Subcon Code Line 2 = Lot Traceability	● WW	Top Mark Line 1= Workweek Line 2 = Lot Traceability ● = Pin 1 indicator
8	WLCSP	●CU XXX YTC	Top Mark Line 1= Device Information Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator	OXX XXX NNN	Top Mark Line 1= Country of Origin Line 2 = Truncation Code Line 3 = Lot Traceability ■ = Pin 1 indicator
		ATML*YWW XXXXXXXX AAAAAA	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator	ATML*YWW XXXXXXXX YYWWNNN •	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability ■ = Pin 1 indicator
31	WLCSP	• XXXXXXXX XXXXXXXX AAAAAA.## X YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Date Code ● = Pin 1 indicator	XXXXXXXX XXXXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Country of Origin, Date Code ■ = Pin 1 indicator

Atmel®				MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
54	WLCSP	XXXXXXXX XXXXXXXX AAAAAA.##	Top Mark Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability ● = Pin 1 indicator	XXXXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code ● = Pin 1 indicator
49 / 64	WLCSP	● Atmel XXXXXXXXXXX XX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ■ = Pin 1 indicator		Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
20	VQFN 3X3 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator	• XXX XXX WNNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability
24 / 28	VQFN 4X4 MM	• XYYWW# XXXXXXX XXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ● = Pin 1 indicator	ATMEL XXXXX XXXX-COO YYWWNNN OR ATMEL XXXXXX XXXXN XXXXN YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ■ = Pin 1 indicator